

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	229474	((transparent or (light emitting) or refract\$4 or clear) (panel or sheet or plate or substrate))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/14 18:04
L3	3159	((laminat\$4 ((transparent or (light emitting) or refract\$4 or clear) (panel or sheet or plate or substrate)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/14 18:05
L4	229474	2 or 3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/14 18:05
L5	18904	((light emitting diode) or "LED") chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/14 18:07
L6	1106524	((light emitting diode) or "LED")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/14 18:07
L7	412	semiconductor light emitting chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/14 18:07

L8	25	(solid state) light emitting chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/14 18:07
L9	1106621	L5 or L6 or L7 or L8	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/14 18:07
L10	60	4 with (opening or hole) with ("in" or "within") with L9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/14 18:07
L11	0	(((((light emitting diode) or "LED") or (((light emitting diode) or "LED") chip) or (semiconductor light emitting chip) or((solid state) light emitting chip)) with ((printed circuit board) or "PCB")) with ("in" or "within") with (opening or hole) with(laminat\$4 ((transparent or (light emitting) or refract\$4 or clear) (panel or sheet or plate or substrate)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/14 18:19
S1	17070	((light emitting diode) or "LED") chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 21:26
S2	1061480	((light emitting diode) or "LED")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 21:26
S4	385	semiconductor light emitting chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 21:27

S5	22	(solid state) light emitting chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 21:28
S6	1061572	S1 or S2 or S4 or S5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 21:28
S7	595921	(circuit board) or ((printed circuit board) or "PCB")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 21:29
S8	559851	circuit with S7	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 21:31
S9	23162	S8 with S6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 21:31
S10	1449	S9 with (capsulat\$4 or capsulant or encased or embed\$4 or laminat\$4 or layer\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 21:33
S11	137	S10 with (transparent or clear or (ligh transmi\$5) or refract\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 21:35

S12	63	S11 and @ad < '20031223'	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 21:36
S13	5	(US-6893258-\$ or US-6743249-\$ or US-6595671-\$).did. or (JP-08202290-\$ or JP-06095064-\$).did.	USPAT; JPO	NEAR	ON	2009/05/13 21:46
S14	74	S11 not S12	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 21:46
S15	8	(US-20090099499-\$ or US-20090032825-\$ or US-20070030662-\$).did. or (US-20090032825-\$ or CN-200972986-\$ or KR-2007102320-\$ or CN-2934891-\$ or KR-2005100083-\$).did.	US-PGPUB; DERWENT	NEAR	ON	2009/05/13 21:57
S16	13	S13 or S15	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 21:57
S17	317	S10 and "362"\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 21:59
S18	243	S10 and "257"\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 21:59
S19	8	S10 and "600"\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 22:02

S20	3	S10 and "604"\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 22:02
S21	8	S10 and "607"\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 22:02
S22	527	S17 or S18 or S19 or S20 or S21	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 22:03
S23	183	S22 and @ad < "20031223"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 22:03
S24	156	S23 not S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 22:03
S25	6	(US-20020143373-\$.)did. or (US-6874901-\$. or US-6059414-\$. or US-5771617-\$. or US-5475241-\$. or US-4965038-\$.)did.	US-PGPUB; USPAT	NEAR	ON	2009/05/13 22:10
S26	19	S16 or S25	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/13 22:11

S27	17104	((light emitting diode) or "LED") chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/14 09:41
S28	1062236	((light emitting diode) or "LED")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/14 09:41
S29	385	semiconductor light emitting chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/14 09:41
S30	22	(solid state) light emitting chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/14 09:41
S31	1062328	S27 or S28 or S29 or S30	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/14 09:41
S32	596344	(circuit board) or ((printed circuit board) or "PCB")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/14 09:41
S33	560258	circuit with S32	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/14 09:41

S34	23197	S33 with S31	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/14 09:41
S35	1684	S34 with (capsulat\$4 or capsulant or encased or embed\$4 or laminat\$4 or layer\$4 or encapsulat\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/14 09:41
S36	173	S34 with (transparent or clear or (ligh transmit\$5) or refract\$4) with (capsulat\$4 or capsulant or encased or embed\$4 or laminat\$4 or layer\$4 or encapsulat\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/14 09:43
S37	79	S36 and @ad < "20031223"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/14 09:44
S38	7	(US-20050009242-\$).did. or (US-6893258-\$ or US-6743249-\$ or US-6595671-\$).did. or (JP-08202290-\$ or JP-06095064-\$).did. or (WO-9724770-\$).did.	US-PGPUB; USPAT; JPO; DERWENT	NEAR	ON	2009/05/14 09:54
S39	5	(US-6893258-\$ or US-6743249-\$ or US-6595671-\$).did. or (JP-08202290-\$ or JP-06095064-\$).did.	USPAT; JPO	NEAR	ON	2009/05/14 09:55
S40	8	(US-20090099499-\$ or US-20090032825-\$ or US-20070030662-\$).did. or (US-20090032825-\$ or CN-200972986-\$ or KR-2007102320-\$ or CN-2934891-\$ or KR-2005100083-\$).did.	US-PGPUB; DERWENT	NEAR	ON	2009/05/14 09:55
S41	13	S39 or S40	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/14 09:55
S42	6	(US-20020143373-\$).did. or (US-6874901-\$ or US-6059414-\$ or US-5771617-\$ or US-5475241-\$ or US-4865038-\$).did.	US-PGPUB; USPAT	NEAR	ON	2009/05/14 09:55

S43	19	S41 or S42	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/14 09:55
S44	21	S38 or S43	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/14 09:55
S45	17185	((light emitting diode) or "LED") chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 09:30
S46	1063520	((light emitting diode) or "LED")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 09:30
S47	386	semiconductor light emitting chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 09:30
S48	22	(solid state) light emitting chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 09:30
S49	1063613	S45 or S46 or S47 or S48	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 09:30

S50	597412	(circuit board) or ((printed circuit board) or "PCB")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 09:30
S51	26058	S50 with S49	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 09:30
S52	1712	S50 and (S49 with (laminat\$4 or embed\$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 09:32
S53	1083	S50 and (S49 with (laminat\$4 or embed\$3)) and (transparent or clear or (ligh transmit\$5) or refract\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 09:34
S54	178	S50 and ((S49 with (laminat\$4 or embed\$3)) with (transparent or clear or (ligh transmit\$5) or refract\$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 09:35
S55	83	S54 and @ad < "20031223"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 09:42
S56	9709	362/153,320,330,471,479,488,490,492,1606,607,608,611- 613,617,619,619,621,630,631,632,543-546,800,806.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 12:15

S57	5207	S56 and S49	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 12:16
S58	78	S56 and S53	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 12:17
S59	38	S58 and @ad < "20031223"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 12:18
S60	88	362/490,479.ccls. and S49	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 12:26
S61	5	(US-20020167820-\$).did. or (US-6666571-\$ or US-6464381-\$ or US-6402354-\$ or US-6203180-\$).did.	US-PGPUB; USPAT	NEAR	ON	2009/05/18 12:52
S62	6	("5079675" "5520434" "6019411" "6331065").PN. OR ("6666571").URPN.	US-PGPUB; USPAT; USOCR	NEAR	ON	2009/05/18 12:54
S63	1	(US-7284886-\$).did.	USPAT	NEAR	ON	2009/05/18 12:57
S64	79	("3545110" "4104555" "4109235" "4138620" "4181925" "4297681" "4328532" "4365232" "4499451" "4561042" "4578617" "4580196" "4581683" "4647337" "4667273" "4754372" "4864473" "4951177" "4959759" "5013967" "5124845" "5142274" "5257167" "5272603" "5329429" "5339550" "5347434" "5414598" "5434013" "5434757" "5441339" "5479275" "5499170" "5504661" "5516143" "5549323" "5558364" "5564813" "5565733" "5566384" "5671996" "5803579" "5811930" "5917666" "5938321" "6008732" "6040534" "6082867" "6086131" "6087953" "6101032" "6111622" "6120159" "6124647" "6132072" "6139172" "6140934" "6144424" "6160475").PN. OR ("6464381").URPN.	US-PGPUB; USPAT; USOCR	NEAR	ON	2009/05/18 12:57
S65	10	("5938321").PN. OR ("6402354").URPN.	US-PGPUB; USPAT; USOCR	NEAR	ON	2009/05/18 13:12

S66	29	("4158223" "4794373" "5661374" "5803579").PN. OR ("6203180").URPN.	US-PGPUB; USPAT; USOCR	NEAR	ON	2009/05/18 13:13
S67	29	("4158223" "4794373" "5661374" "5803579").PN. OR ("6203180").URPN.	US-PGPUB; USPAT; USOCR	NEAR	ON	2009/05/18 13:21
S68	29	("4158223" "4794373" "5661374" "5803579").PN. OR ("6203180").URPN.	US-PGPUB; USPAT; USOCR	NEAR	ON	2009/05/18 13:22
S69	1	(US-7163305-\$).did.	USPAT	NEAR	ON	2009/05/18 13:22
S70	29	("4158223" "4794373" "5661374" "5803579").PN. OR ("6203180").URPN.	US-PGPUB; USPAT; USOCR	NEAR	ON	2009/05/18 13:23
S71	25	("3755663" "4104555" "4143297" "4159559" "4608308" "4631650" "4654765" "4661373" "4719405" "4994944" "5051654" "5144117").PN. OR ("5661374").URPN.	US-PGPUB; USPAT; USOCR	NEAR	ON	2009/05/18 13:24
S72	2	(US-7163305-\$ or US-5661374-\$).did.	USPAT	NEAR	ON	2009/05/18 13:26
S73	7	(US-20050009242-\$).did. or (US-6893258-\$ or US-6743249-\$ or US-6595671-\$). did. or (JP-08202290-\$ or JP-06095064-\$).did. or (WO-9724770-\$).did.	US-PGPUB; USPAT; JPO; DERWENT	NEAR	ON	2009/05/18 13:27
S74	5	(US-6893258-\$ or US-6743249-\$ or US-6595671-\$).did. or (JP-08202290-\$ or JP- 06095064-\$).did.	USPAT; JPO	NEAR	ON	2009/05/18 13:27
S75	8	(US-20090099499-\$ or US-20090032825-\$ or US-20070030662-\$).did. or (US- 20090032825-\$ or CN-200972986-\$ or KR-2007102320-\$ or CN-2934891-\$ or KR- 2005100083-\$).did.	US-PGPUB; DERWENT	NEAR	ON	2009/05/18 13:27
S76	13	S74 or S75	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 13:27
S77	6	(US-20020143373-\$).did. or (US-6874901-\$ or US-6059414-\$ or US-5771617-\$ or US-5475241-\$ or US-4865038-\$).did.	US-PGPUB; USPAT	NEAR	ON	2009/05/18 13:27
S78	19	S76 or S77	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 13:27

S79	21	S73 or S78	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 13:27
S80	16	S69 or S72 or S63 or S79	US-PGPUB; USPAT; USOCR	NEAR	ON	2009/05/18 13:27
S81	3	(US-7284886-\$ or US-7163305-\$ or US-5661374-\$).did.	USPAT	NEAR	ON	2009/05/18 13:33
S82	2	("6890089").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/18 13:33
S83	1	(US-6890089-\$).did.	USPAT	NEAR	ON	2009/05/18 13:34
S84	5	S81 or S82	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 13:35
S85	4	(US-7284886-\$ or US-7163305-\$ or US-5661374-\$ or US-6890089-\$).did.	USPAT	NEAR	ON	2009/05/18 13:35
S95	17185	((light emitting diode) or "LED") chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 19:34
S96	1063520	((light emitting diode) or "LED")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 19:34

S97	386	semiconductor light emitting chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 19:34
S98	22	(solid state) light emitting chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 19:34
S99	1063613	S95 or S96 or S97 or S98	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 19:34
S100	597412	(circuit board) or ((printed circuit board) or "PCB")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 19:34
S101	145	S100 and ((S99 with (laminat\$4 or embed\$3)) with (transparent or clear or (ligh transmit\$5 or refract\$4)) and (housing or case or casing)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 19:34
S102	65	S101 and @ad < "20031223"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/18 19:35
S103	12	("20020167820" "20020172039" "20050073851" "20050128760" "5101325" "6152569" "6240664" "6331065" "6666571" "6742907" "6890089" "7118239").PN. OR ("7284886").URPN.	US-PGPUB; USPAT; USOCR	NEAR	ON	2009/05/18 19:40
S104	29	("4158223" "4794373" "5661374" "5803579").PN. OR ("6203180").URPN.	US-PGPUB; USPAT; USOCR	NEAR	ON	2009/05/18 19:58
S105	3	"6890089"	US-PGPUB; USPAT; USOCR	NEAR	ON	2009/05/18 20:00

S106	2	"20080259623"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 09:40
S107	1	S106 and integrat\$3 and laminat\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 09:40
S108	1	S106 and integrat\$3 and laminat\$4 and (output element)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 10:11
S109	1	S106 and (output element)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 10:11
S111	17195	((light emitting diode) or "LED") chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 10:50
S112	1063914	((light emitting diode) or "LED")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 10:50
S113	386	semiconductor light emitting chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 10:50

S114	22	(solid state) light emitting chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 10:50
S115	1064007	S111 or S112 or S113 or S114	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 10:50
S116	77656	(laminat\$4 glass) or (layer\$4 glass)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 10:51
S117	689	(laminat\$4 glass panel) or (layer\$4 glass panel)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 10:52
S118	77656	S116 or S117	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 10:52
S119	6066	S115 and S118	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 10:52
S120	24	S115 with "in" with S118	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 10:53

S121	7	S115 with 'within' with S118	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 10:53
S122	31	S120 or S121	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 10:54
S123	9	("20020024981" "20030025572" "20030087463" "4643532" "5376580" "6287882" "6292243" "6417478" "6861281").PN. OR ("7119375").URPN.	US-PGPUB; USPAT; USOCR	NEAR	ON	2009/05/19 11:28
S124	6	("2552955").URPN.	USPAT	NEAR	ON	2009/05/19 11:30
S125	0	day-stephen-\$.in	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 12:58
S126	37	day-stephen-\$.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 12:59
S127	0	"gb-0216787.2-".\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 13:03
S128	0	"GB-0216787-".\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 13:04

S129	0	GB-0216787-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 13:04
S130	0	GB-02167872-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 13:04
S131	0	"02167872"	FPRS; EPO	NEAR	ON	2009/05/19 13:05
S132	27	DAY-STEPHEN.IN.	FPRS; EPO	NEAR	ON	2009/05/19 13:06
S133	12	("20010055458" "3317906" "4636698" "4761720" "4968895" "5193895" "5650208" "5890794" "6208031" "6270236" "6281525" "6361867").PN.	US-PGPUB; USPAT	NEAR	ON	2009/05/19 13:27
S134	32	("3317906").URPN.	USPAT	NEAR	ON	2009/05/19 13:30
S135	2	((("3317906") or ("6361867"))).PN.	USPAT	OR	OFF	2009/05/19 14:27
S136	1	(US-6361867-\$.did.	USPAT	NEAR	ON	2009/05/19 14:29
S137	1	DE-4431890-\$.D.ID.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 14:30
S138	1	(GB-2281683-\$.did.	DERWENT	NEAR	ON	2009/05/19 14:31
S139	0	JP-2084684-\$.did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 14:33

S140	1	JP-02084684-\$.dtd.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 14:33
S141	2	S137 or S138 or S140	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/05/19 14:37
S142	10099	362/153,320,330,471,479,488,490,492,1606,607,608,611-613,617,619,619,621,630,631,632,543-546,800,806.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/09 12:10
S143	18875	((light emitting diode) or "LED") chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/09 12:10
S144	1105443	((light emitting diode) or "LED")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/09 12:10
S145	410	semiconductor light emitting chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/09 12:10
S146	25	(solid state) light emitting chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/09 12:10

S147	1105540	S143 or S144 or S145 or S146	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/09 12:10
S148	624359	(circuit board) or ((printed circuit board) or "PCB")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/09 12:13
S149	1167	S148 and ((S147 with (laminat\$4 or embed\$3)) and (transparent or clear or (ligh transmit\$5) or refract\$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/09 12:13
S150	194	S148 and ((S147 with (laminat\$4 or embed\$3)) with (transparent or clear or (ligh transmit\$5) or refract\$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/09 12:13
S151	1167	S149 or S150	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/09 12:13
S152	91	362/490,479.ccls. and S147	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/09 12:19
S153	83023	S147 and S148	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/09 15:15

S154	177	(transparent or clear or (ligh transmit\$5) or refract\$4) ((panel or plate) area)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/09 15:22
S155	69540	(transparent or clear or (ligh transmit\$5) or refract\$4) (panel or plate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/09 15:23
S156	7644	S155 with (recess or opening or hole)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	NEAR	ON	2009/11/09 15:24

EAST Search History (Interference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L13	0	(((((light emitting diode) or "LED") or (((light emitting diode) or "LED") chip) or (semiconductor light emitting chip) or (solid state) light emitting chip)) with ((printed circuit board) or "PCB")) with ("in" or "within") with (opening or hole) with (laminat\$4 ((transparent or (light emitting) or refract\$4 or clear) (panel or sheet or plate or substrate)))	USPAT; UPAD	NEAR	ON	2009/11/14 18:20

11/14/2009 6:20:41 PM

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